

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	192		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3	
		18	L2		
C-RS-FR4-ML-0.203mm-018+018-TG150-HF-...	50203027	203		4	A01
		18	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	230		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	B00
		18	L4		
C-RS-FR4-ML-0.203mm-018+018-TG150-HF-...	50203027	203		7	A02
		18	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	192		8	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		9	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	10	

Thickness after Pressing

B00:

1090 µm

Tol+:

120 µm

Tol-:

120 µm

Dmax:

1210 µm

Dmin:

970 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1200 µm

Tol+:

120 µm

Tol-:

120 µm

Dmax:

1320 µm

Dmin:

1080 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1128 µm

Version 1.2.20.35

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